

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re U.S. Patent Application of)

Yokogawa et al.)

Application Number: To Be Assigned)

Filed: Concurrently Herewith)

For: METHOD FOR MANUFACTURING A)
SEMICONDUCTOR DEVICE)

Honorable Assistant Commissioner
for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Applicant has amended the claims in order to remove the multiple dependencies contained therein in accordance with standard U.S. practice, thereby reducing the basic filing fee. No new matter has been added to the application as a result of this amendment. Prior to an examination on the merits, please amend the above-identified application as follows:

IN THE CLAIMS:

Please substitute claim 3 currently on file with the following amended claim:

3. (Amended) The method according to claim 1, wherein said substrate is a semiconductor wafer.

Please add the following new claim:

40. (Added) The method according to claim 2, wherein said substrate is a semiconductor wafer.